

IN THE CLAIMS:

Claims 1 through 7 are canceled herein. Claim 8 has been amended herein, and new claims 18 through 24 have been added. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1-7. (Canceled)

8. (Currently Amended) ~~The electronic device package according to claim 1, An~~
electronic device package comprising:
a transparent substrate;
a plurality of conductive traces formed on a surface of the transparent substrate, each conductive
trace of the plurality of conductive traces having a first attachment point and a second
attachment point;
an optically interactive electronic device having at least one bond pad, the optically interactive
electronic device mounted to the transparent substrate by a bond between the first
attachment point of a conductive trace of the plurality of conductive traces and the at least
one bond pad;
a backing cap covering a back surface of the optically interactive electronic device, the backing
cap having at least one backing cap attachment point in electrical communication with the
second attachment point of the conductive trace and at least one attachment pad on a
surface of the backing cap in electrical communication with the at least one backing cap
attachment point; and
wherein the transparent substrate comprises a single substrate having multiple optically
interactive electronic devices mounted thereto.

9. (Previously Presented) An electronic device package comprising:
a transparent substrate;
a secondary substrate secured by a first surface thereof to a surface of the transparent substrate having a central aperture covered by the transparent substrate and a plurality of conductive traces formed around the central aperture, each conductive trace of the plurality of conductive traces having a first attachment point and a second attachment point on a second surface of the secondary substrate;
an optically interactive electronic device having at least one bond pad, the optically interactive electronic device mounted to the secondary substrate by a bond between the first attachment point of a conductive trace of the plurality of conductive traces and the at least one bond pad; and
a backing cap covering a back surface of the optically interactive electronic device, the backing cap having at least one backing cap attachment point in electrical communication with the second attachment point of the conductive trace and at least one attachment pad on a surface of the backing cap in electrical communication with the at least one backing cap attachment point.

10. (Original) The electronic device package according to claim 9, further comprising:
a bond between the at least one backing cap attachment point and the second attachment point of the conductive trace, the bond comprising one of a conductive or conductor-filled epoxy, a solder joint and a layer of anisotropically conductive adhesive material.

11. (Original) The electronic device package according to claim 9, further comprising:
an array of attachment pads on the surface of the backing cap.

12. (Original) The electronic device package according to claim 9, further comprising:
a discrete conductive element disposed on the at least one attachment pad on the surface of the backing cap.
13. (Original) The electronic device package according to claim 12, wherein the discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.
14. (Original) The electronic device package according to claim 9, wherein the secondary substrate comprises one of a printed circuit board, a polyimide film a ceramic and silicon.
15. (Original) The electronic device package according to claim 9, wherein an outside perimeter of the secondary substrate is substantially equal to an outside perimeter of the transparent substrate.
16. (Original) The electronic device package according to claim 9, wherein the optically interactive electronic device comprises an image sensor.
17. (Original) The electronic device package according to claim 9, wherein the transparent substrate comprises a single substrate having a plurality of optically interactive electronic devices mounted thereto.

Please add the following new claims:

18. (New) The electronic device package according to claim 8, further comprising:
a bond between the at least one backing cap attachment point and the second attachment point of
the conductive trace, the bond comprising one of a conductive or conductor-filled epoxy,
a solder joint and a layer of anisotropically conductive adhesive material.
19. (New) The electronic device package according to claim 8, further comprising:
an array of attachment pads on the surface of the backing cap.
20. (New) The electronic device package according to claim 8, further comprising:
a discrete conductive element disposed on the at least one attachment pad on the surface of the
backing cap.
21. (New) The electronic device package according to claim 20, wherein the discrete
conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a
conductor-filled epoxy.
22. (New) The electronic device package according to claim 8, wherein the secondary
substrate comprises one of a printed circuit board, a polyimide film a ceramic and silicon.
23. (New) The electronic device package according to claim 8, wherein an outside
perimeter of the secondary substrate is substantially equal to an outside perimeter of the
transparent substrate.
24. (New) The electronic device package according to claim 8, wherein the optically
interactive electronic device comprises an image sensor.